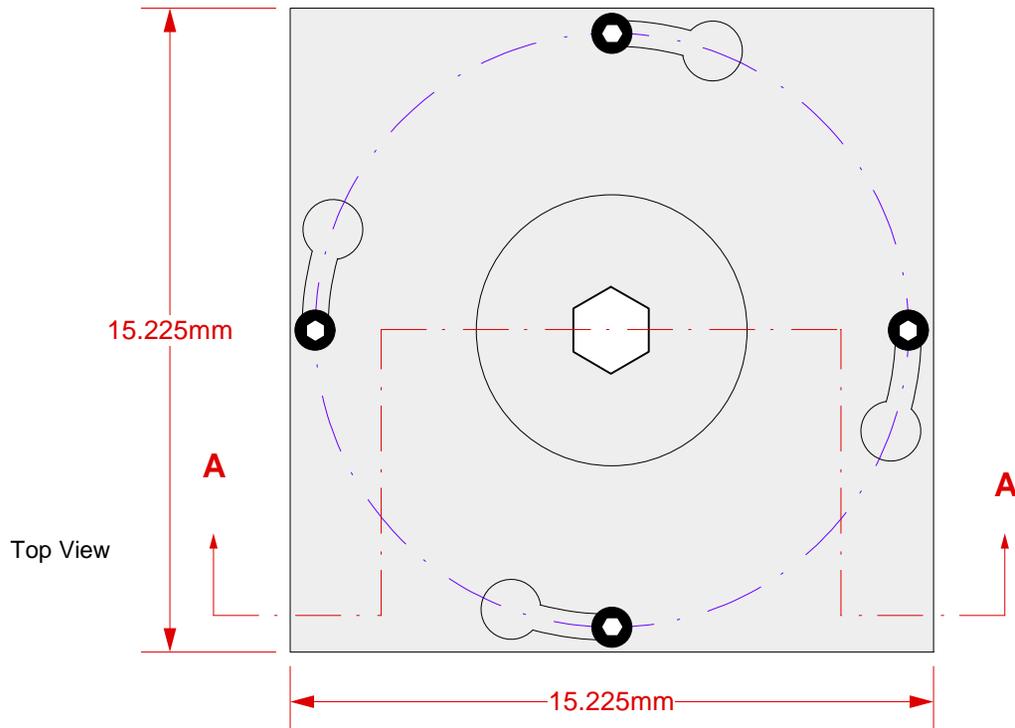


GHz BGA Socket - Direct mount, solderless

Features

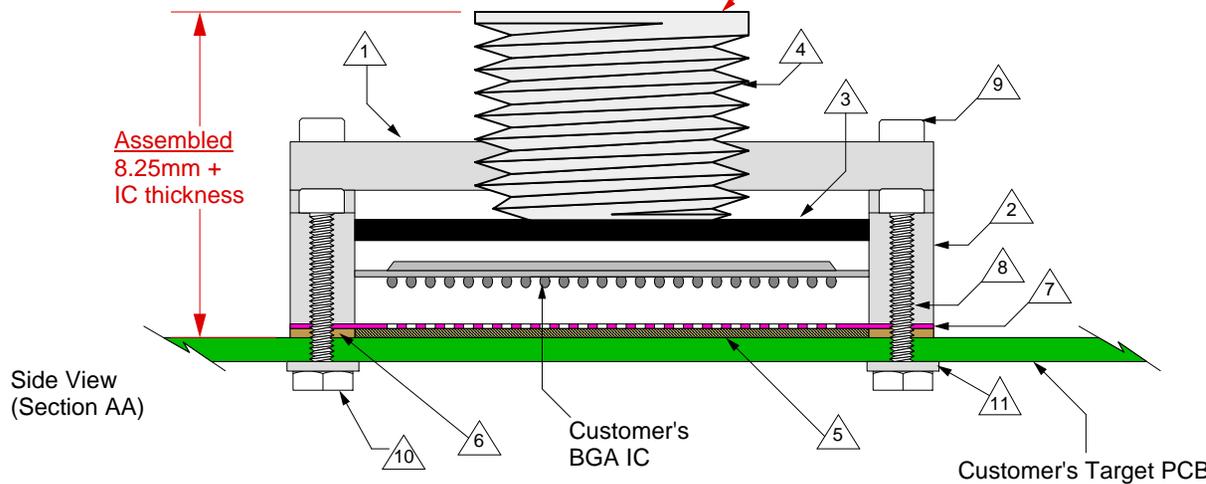
- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid



Top View

- 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- 4 Compression screw: Black anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- 6 Elastomer Guide: Non-clad FR4. Thickness = 0.725mm.
- 7 Ball Guide: Kapton polyimide.
- 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- 10 Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
- 11 Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thickness.

Recommended torque = 0.5 in-lb



Side View
(Section AA)

SG-BGA-6034 Drawing

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PO BOX 21151 ST. PAUL, MN 55121
Tele: (651) 452-8100
www.ironwoodelectronics.com

Status: Released

Scale: - N/A

Rev: D

Drawing: H. Hansen

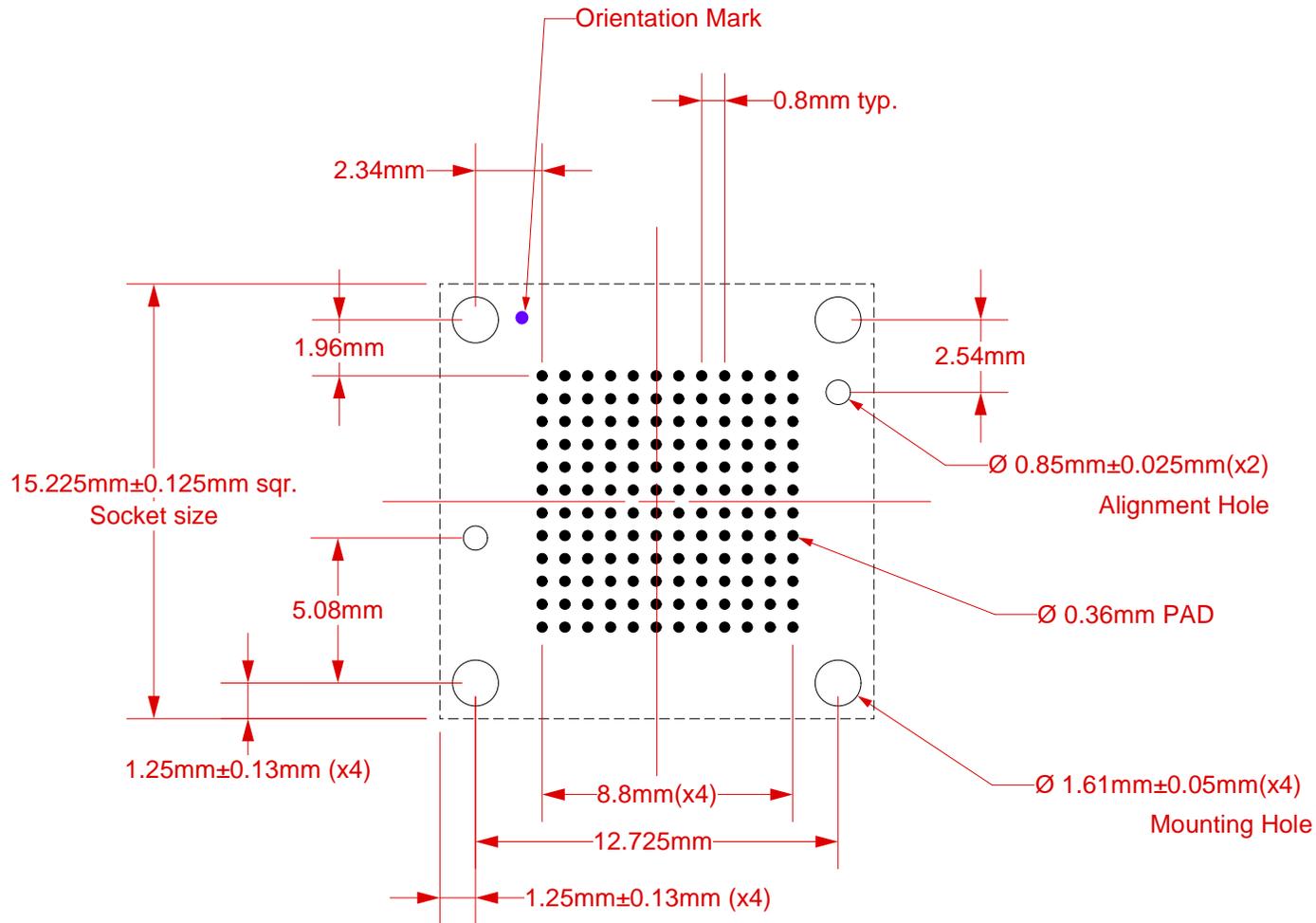
Date: 3/5/02

File: SG-BGA-6034 Dwg.mcd

Modified: 6/2/09

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**



Target PCB Recommendations

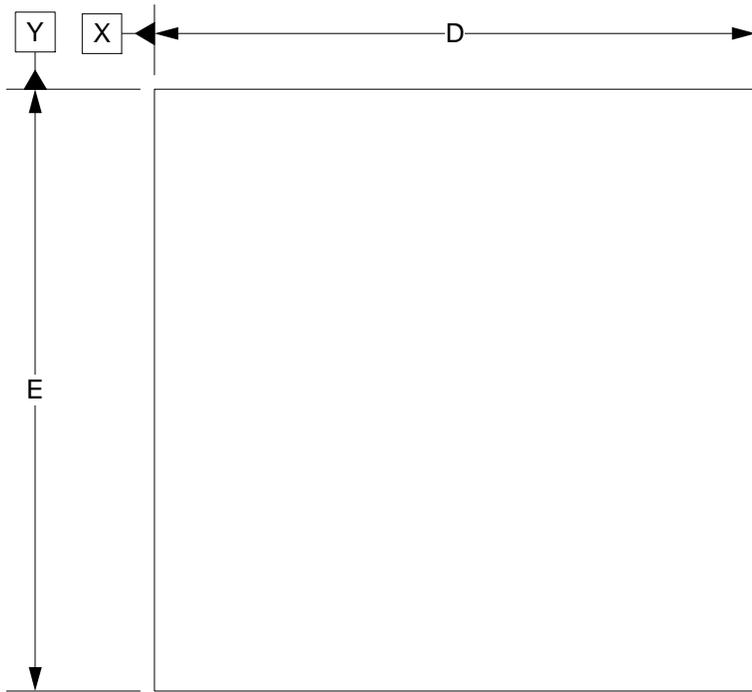
- Total thickness: 1.6mm min.
- Plating: Gold or Solder finish
- PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

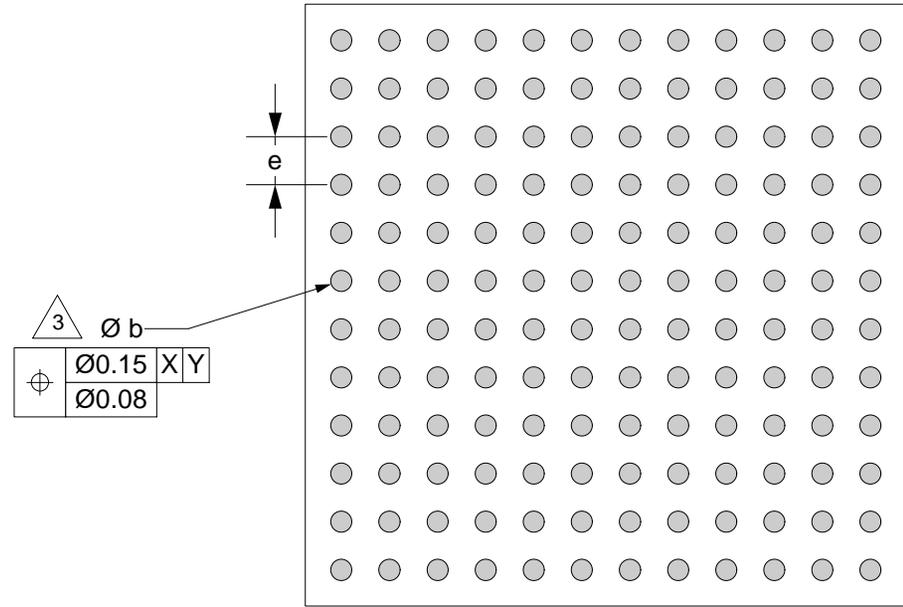
Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

	SG-BGA-6034 Drawing	Status: Released	Scale: 4:1	Rev: D
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		File: SG-BGA-6034 Dwg.mcd	Modified: 6/2/09	

Compatible BGA Spec

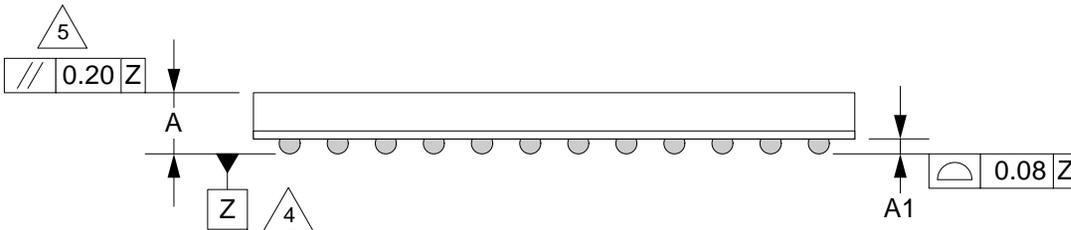


Top View



Bottom View

Array: 12x12



End View

1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- $\triangle 3$ Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - $\triangle 4$ Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - $\triangle 5$ Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		1.2
A1	0.18	0.28
b		0.35
D	10.0 BSC	
E	10.0 BSC	
e	0.8 BSC	

SG-BGA-6034 Drawing

Status: Released

Scale: - N/A

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